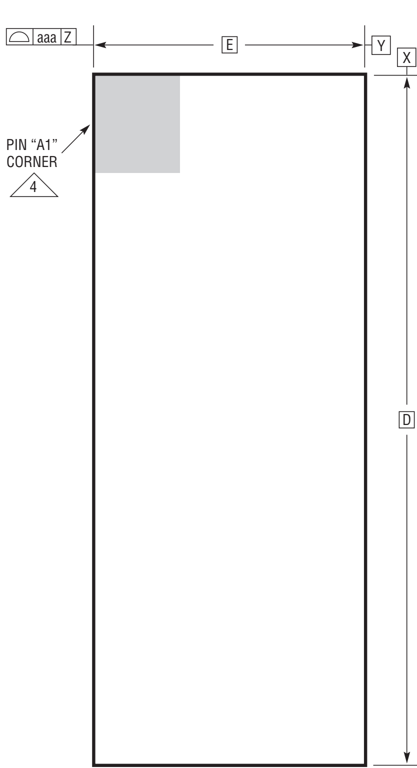
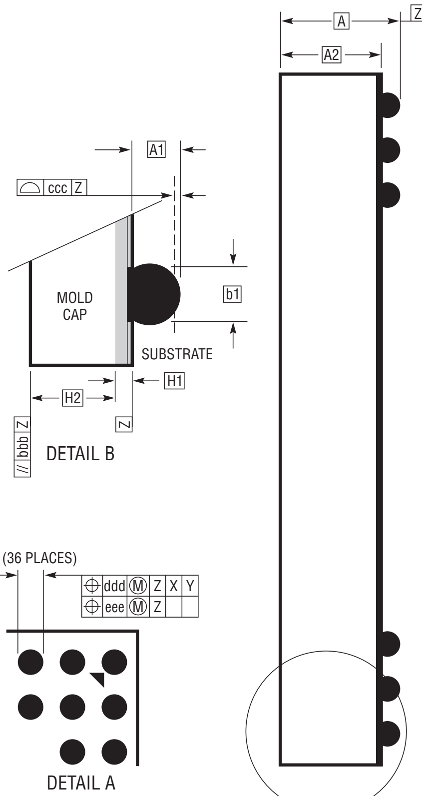
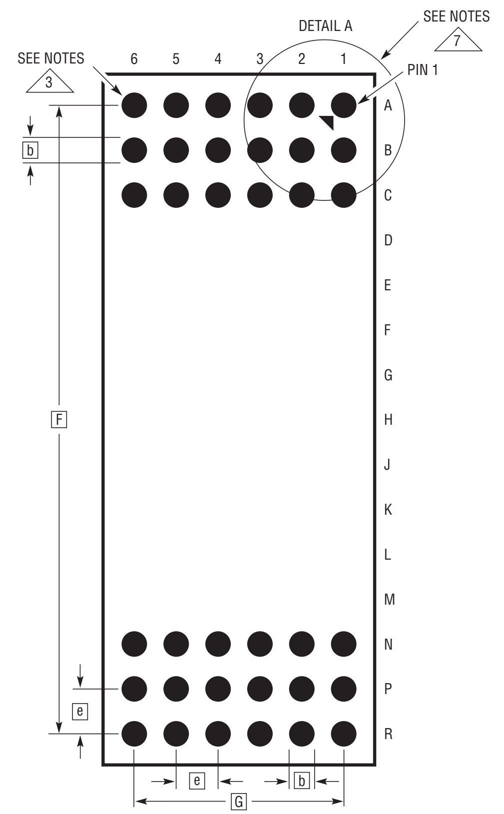
BGA Package
36-Lead (15mm × 6.25mm × 2.06mm)
(Reference LTC DWG# 05-08-1987 Rev Ø)



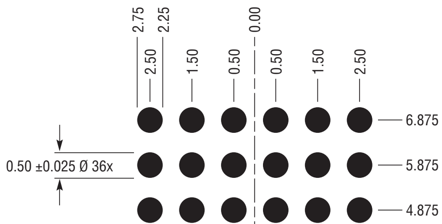
PACKAGE TOP VIEW



DETAIL B
PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW



0.00

4.875

5.875

6.875

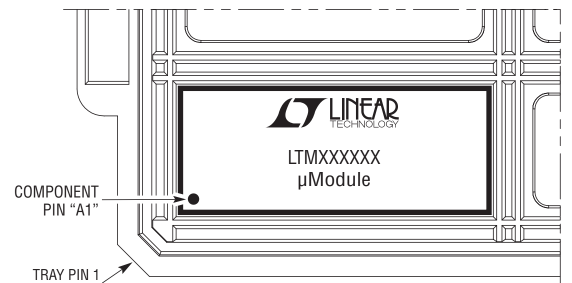
6.675

6.125

SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	1.86	2.06	2.26	
A1	0.40	0.50	0.60	
A2	1.46	1.56	1.66	
b	0.45	0.60	0.75	
b1	0.47	0.50	0.53	
D		15.00		
E		6.25		
e		1.00		
F		13.75		
G		5.00		
H1	0.51	0.56	0.61	
H2	0.95	1.00	1.05	
aaa			0.15	
bbb			0.10	
ccc			0.15	
ddd			0.15	
eee			0.08	
TOTAL NUMBER OF BALLS: 36				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JESD MS-028 AND JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 36 0914 REV Ø